

IN THE CLAIMS:

1. (Currently Amended) A gas discharge display panel comprising a substrate display electrodes, a dielectric layer, and a protective layer, the dielectric layer and the protective layer being formed in the stated order on a surface of the substrate, wherein the protective layer has a first protective film and a second protective film, the second protective film is formed on at ~~least part of a surface of the first protective film~~ so that, under each of the display electrodes, at least part of the surface of the first protective film is exposed, and the first protective film has a larger impurity content than the second protective film.

2. (Original) The gas discharge display panel of claim 1, wherein the second protective film is formed on an entirety of the surface of the first protective film.

3. (Cancelled)

4. (Currently Amended) ~~[[The]] A gas discharge display panel of claim 3,~~
comprising a substrate, display electrodes, a dielectric layer, a protective layer, the dielectric layer and the protective layer being formed in the stated order on a surface of the substrate,
wherein

the protective layer has a first protective film and a second protective film, the second protective film is formed on a surface of the first protective film so that, under each of the display electrodes, at least part of the surface of the first protective film is exposed, and the first protective film has a larger impurity content than the second protective film, and

an area ratio of an overlapping part of the second protective film with the first protective film under the display electrodes is in a range of 10% to 90% inclusive.

5. (Original) The gas discharge display panel of claim 1, wherein a film thickness of the second protective film is in a range of 10 nm to 1 μ m inclusive.

6. (Original) The gas discharge display panel of claim 1, wherein a film thickness of the second protective film is in a range of 10 nm to 100 nm inclusive.

7. (Original) The gas discharge display panel of claim 1, wherein the impurity contained in the first protective film is at least one of H, Cl, F, Si, Ge, and Cr.

8. (Original) The gas discharge display panel of claim 1, wherein the impurity content of the first protective film is in a range of 10 ppm to 10000 ppm inclusive.

9. (Original) The gas discharge display panel of claim 1, wherein each of the first protective film and the second protective contains at least one metal oxide material selected from the group consisting of MgO, CaO, BaO, SrO, MgNO, and ZnO.

10. (Original) The gas discharge display panel of claim 9, wherein each of the first protective film and the second protective film contains MgO.

11. (Currently Amended) [[The]] A gas discharge display panel of claim 9, wherein comprising a substrate, a dielectric layer, and a protective layer, the dielectric layer and the protective layer being formed in the stated order on a surface of the substrate, wherein the protective layer has a first protective film and a second protective film, the second protective film is formed on at least part of a surface of the first protective film, and the first protective film has a larger impurity content than the second protective film.

each of the first protective film and the second protective film contains at least one metal oxide material selected from the group consisting of MgO, CaO, BaO, SrO, MgNO, and ZnO, and

the first protective film contains BaO, and the second protective film contains MgO.

12. (Original) The gas discharge display panel of claim 1, wherein the second protective film is formed in one of island-like formation or in stripe formation.

13. (Currently Amended) A manufacturing method of a gas discharge display panel, the manufacturing method comprising:

a display-electrode forming step of forming a plurality of pairs of display electrodes on a first substrate;

a dielectric-layer forming step of forming a dielectric layer to cover the pairs of display electrodes;

a protective-layer forming step of forming a protective layer on a surface of the dielectric layer; and

a substrate-arranging step of arranging a second substrate to oppose the first substrate with a distance therebetween, wherein

in the protective-layer forming step, the protective layer is formed by forming a first protective layer on the surface of the dielectric layer under a condition where an atmospheric air is blocked, and then by forming a second protective film on at least part of a surface of the first protective film so that, under each of display electrodes, at least part of the surface of the first protective film is exposed under the condition where an atmospheric air is

blocked, the first protective film having a larger impurity content than the second protective layer.

14. (Original) The manufacturing method of claim 13, wherein in the protective-layer forming step, at least one of the first protective film and the second protective film is formed using a sputtering method.